

APPLICATION DATA SHEET**Inventor Information**

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Application Information

Title : STRUCTURE AND METHOD FOR FORMING A
 CAPACITIVELY COUPLED CHIP-TO-CHIP SIGNALING
 INTERFACE
 Total Drawing Sheets : 4
 Formal Drawings : YES
 Application Type : Utility
 Attorney Docket Number : 501340.02 (30327/US)
 Assigned : Yes (Large Entity)

Representative Information

Representative Customer No. : 27,076

Prior Foreign Application

Foreign Application One : 0323992.8
 Filing Date : October 13, 2003
 Country : United Kingdom
 Priority Claimed : Yes